

The Intel logo is displayed in white lowercase letters on a dark blue background.

# Mission Moore's Law

Pat Gelsinger  
CEO, Intel

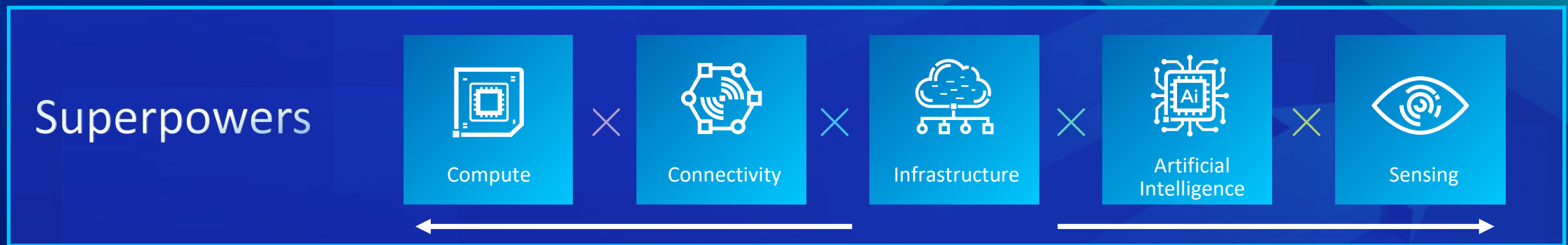
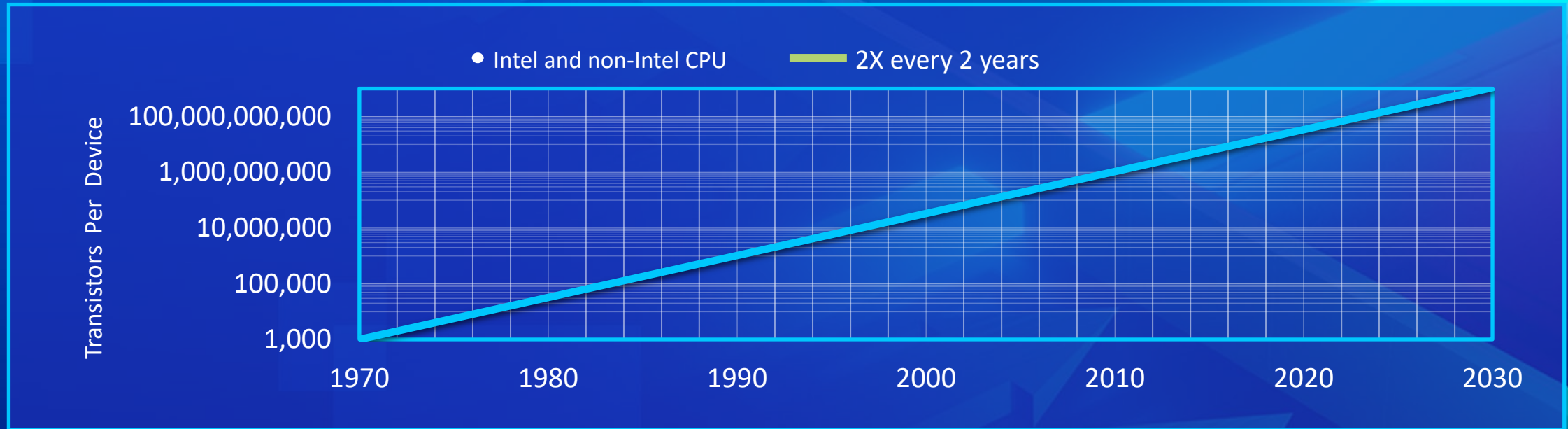


# A Foundation for Improving Lives



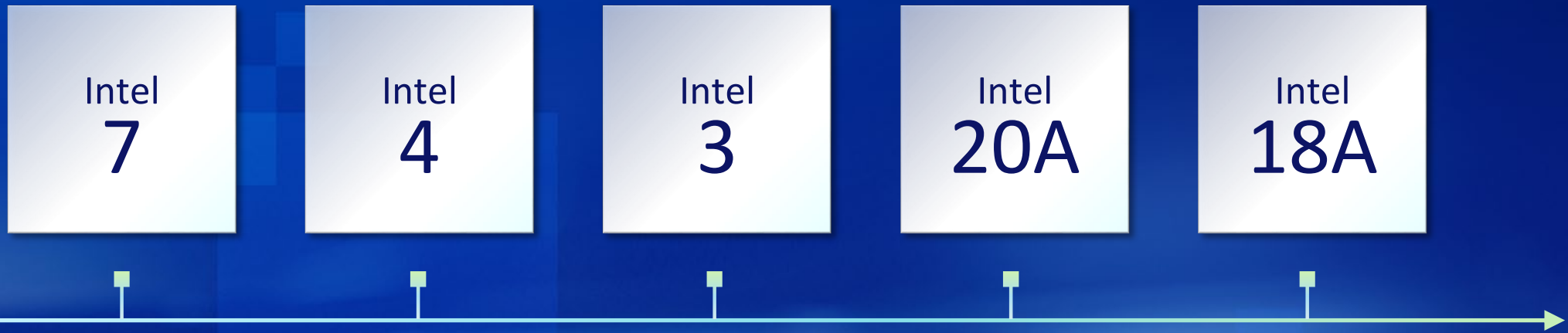
Government, Industry and Academic Partnerships

# Moore's Law is alive and well



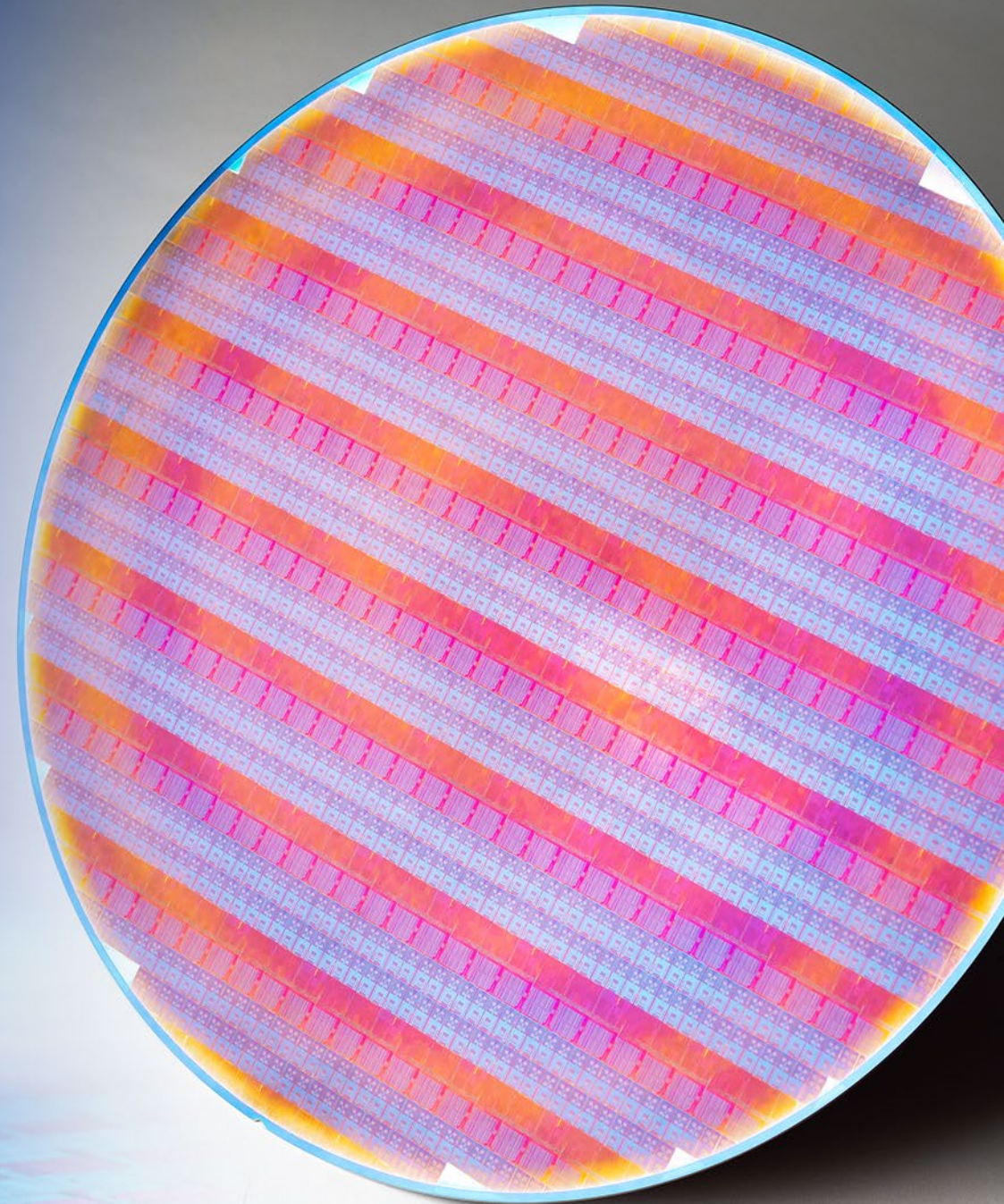
# Innovation Timeline

## 5 Nodes in 4 years



# Innovation Timeline

## 5 Nodes in 4 years



# Moore's Predicted "Day of Reckoning"

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"It may prove to be more economical to build large systems out of smaller functions, which are separately packaged and interconnected<sup>1</sup>."

-Gordon E. Moore

<sup>1</sup>: "[Cramming more components onto integrated circuits](#)", Electronics, Volume 38, Number 8, April 19, 1965



# Intel Package Technology

## ADVANCED PACKAGING ERA



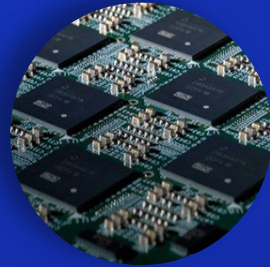
Time

# Research & Development

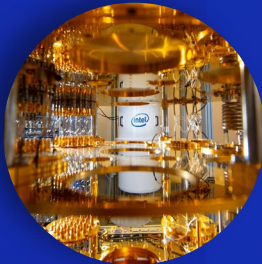
## Compute & Systems Innovation



Autonomous  
Systems



Neuromorphic  
Computing



Quantum  
Computing



AI / Machine  
Learning

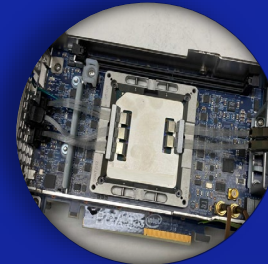
## Innovation in Capabilities



Heterogeneous Package  
Integration



More Secure,  
Domestic Source of  
Custom Chips



Next-gen Optical Interfaces



Homomorphic  
Encryption



# Current Semiconductor Supply Chain

Global Manufacturing Capacity 2020

United States  
12%

Europe  
8%

Asia  
80%

Source: Kearney 2021



# Current Semiconductor Supply Chain

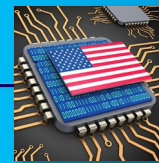
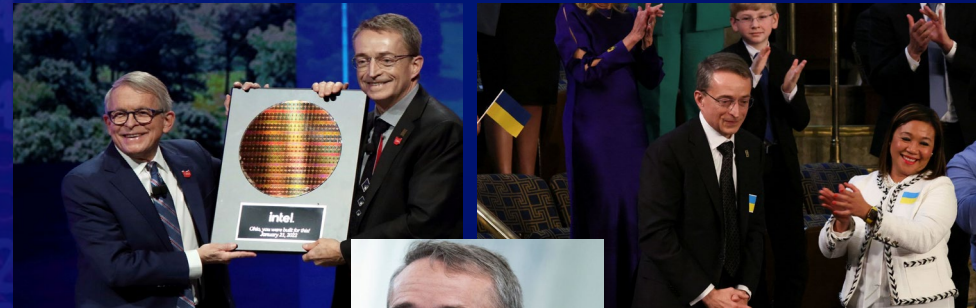
Global Manufacturing Capacity 2020

Moonshot Goal:

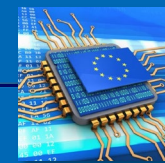
50%

of the world's semi manufacturing  
in the U.S. and the E.U. by 2030

# CHIPS Act



CHIPS  
for America



European  
CHIPS

# \$150 Billion in Past and Planned Investments



Oregon



Ohio



Arizona



New Mexico



Rapid Assured Microelectronics  
Prototypes - Commercial

## RAMP-C

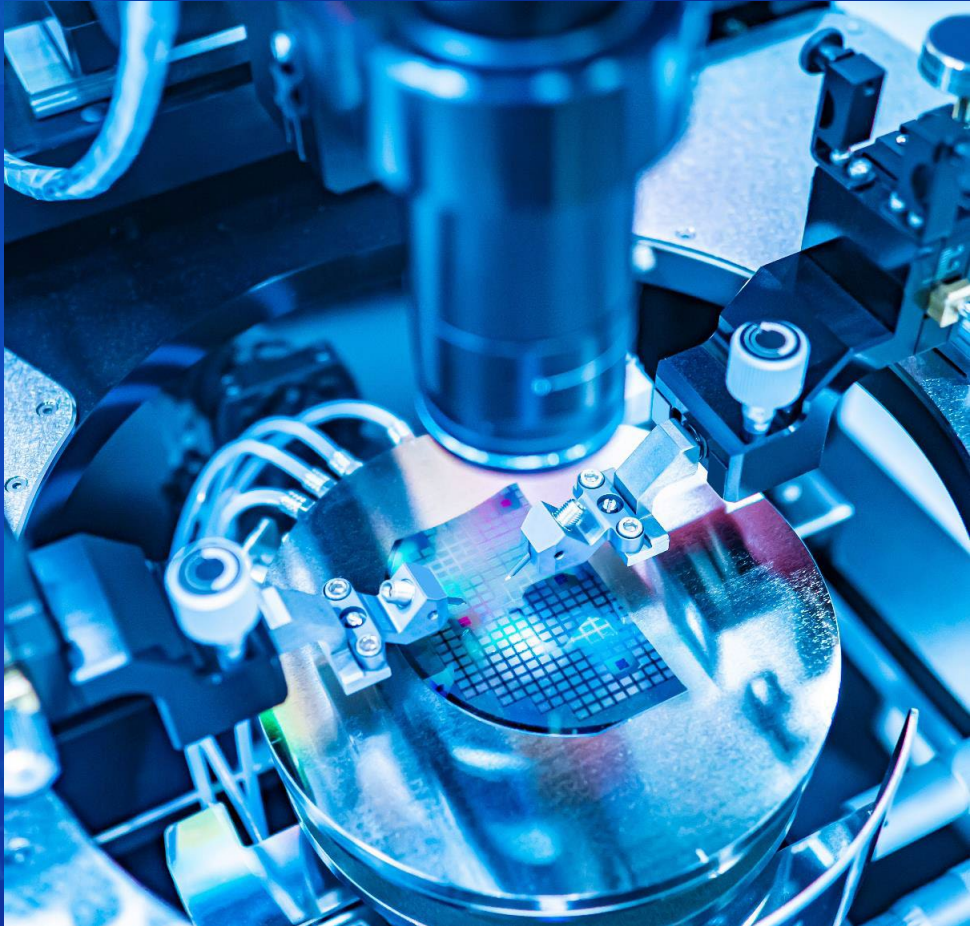
Enabling a U.S.-based commercial semiconductor foundry ecosystem to fabricate leading-edge custom integrated circuits and commercial products required for critical DoD systems.

Intel and DOD Deliver

## SHIP Program

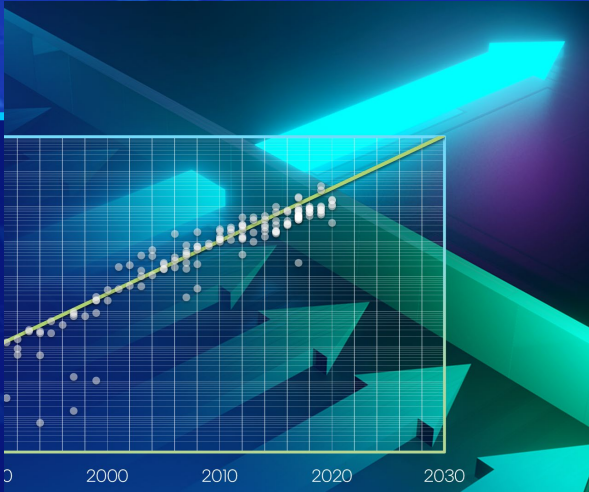
Enables DoD and DIBs access to advanced semiconductor packaging and chiplet libraries, to quickly specify, prototype, build, test and incorporate advanced devices into field equipment.





# University Shuttle Program Spurring advanced semiconductor R&D

# Intel is committed to:



Pushing the boundaries  
of what's possible  
through exceptional  
engineering



Embracing limitless  
opportunities to enhance  
national security through  
collaborative innovation



Building a resilient and  
sustainable future you  
can confidently trust

intel

Thank You





The image features the Intel logo in white lowercase letters, centered on a dark blue background. The background is decorated with a grid of squares in various shades of blue, creating a digital or pixelated effect. The logo itself is a simple, sans-serif font with a registered trademark symbol (®) at the end.

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